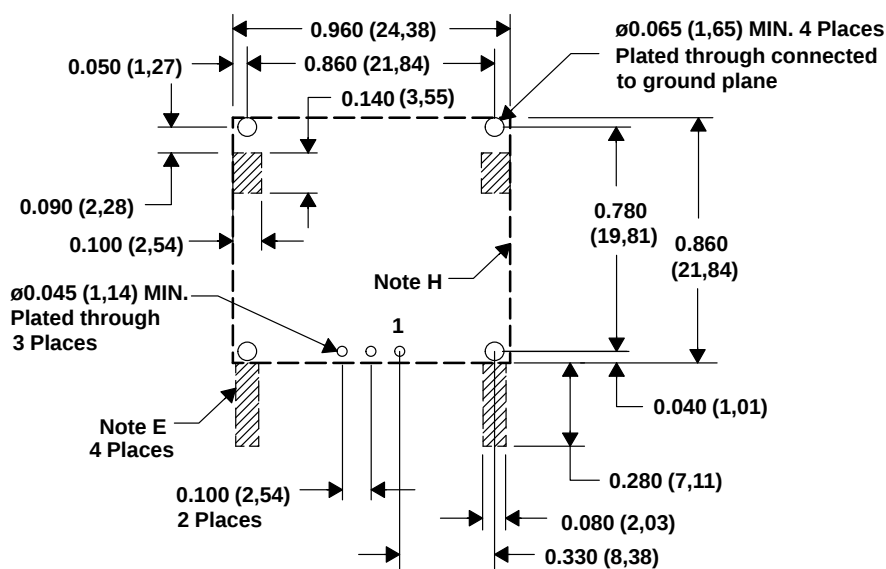
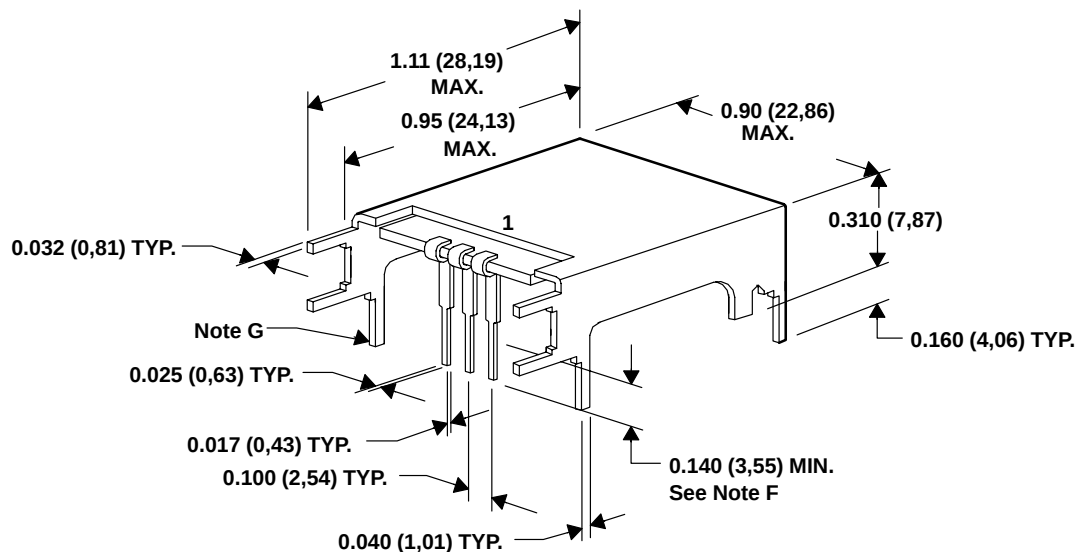


EFP (R-MSIP-T3)

METAL SINGLE-IN-LINE MODULE

Suffix A



PC LAYOUT (TOP VIEW)

4204574/A 07/02

- NOTES:
- A. All linear dimensions are in inches (mm).
 - B. This drawing is subject to change without notice.
 - C. 2 place decimals are ± 0.030 ($\pm 0,76$ mm).
 - D. 3 place decimals are ± 0.010 ($\pm 0,25$ mm).
 - E. Recommended mechanical keep out area.
 - F. Electrical pin length mounted on circuit board seating plane to pin end.
 - G. Electrically connect case to ground plane.
 - H. Case outline reference

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